(2) an electroluminescent lamp panel including spaced transparent and base electrodes with dielectric and phosphorescent layers therebetween surrounded by an envelope of insulating plastic, a conductive lead from each transparent electrode of the lamp panel arranged along a surface of the envelope and a conductive lead from the base electrode of the lamp panel arranged along a surface of the envelope; and wherein

(3) the electroluminescent lamp panel is attached to the first circuit layer or the second circuit layer with each conductive lead of the electroluminescent lamp panel electrically connected to a conductive pad on the circuit layer, and a conductive track on such circuit layer leading from each conductive pad to a tail portion for connection to electrical circuitry.

2. A membrane switch-electroluminescent lamp panel assembly according to claim **1**, wherein: the circuit layer to which the lamp panel is attached includes a first portion carrying the conductive circuit for the membrane switch and a second portion alongside the first portion carrying the conductive pads, and the lamp panel is attached to the second portion of said circuit layer.

3. A membrane switch-electroluminescent lamp panel assembly according to claim **1**, wherein: the circuit layer to which the lamp panel is attached is a lower layer of the assembly.

4. A membrane switch-electroluminescent lamp panel assembly according to claim **1**, wherein: the circuit layer to which the lamp panel is attached is an upper layer of the assembly.

5. A membrane switch-electroluminescent lamp panel assembly according to claim **1**, wherein: both the first circuit layer and the second circuit layer each include

(1) a first portion carrying a conductive circuit for the membrane switch, and

(2) a second portion alongside the first portion and carrying at least one conductive pad, and

the lamp panel is attached to both the first and second circuit layers along the second portion of each circuit layer with its conductive leads electrically connected to conductive pads on each circuit layer.

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